

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE6050KA uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =60V,I_D =50A

 $R_{DS(ON)}$ <13.8m Ω @ V_{GS} =10V

 $R_{DS(ON)}$ <19.2m Ω @ V_{GS} =4.5V

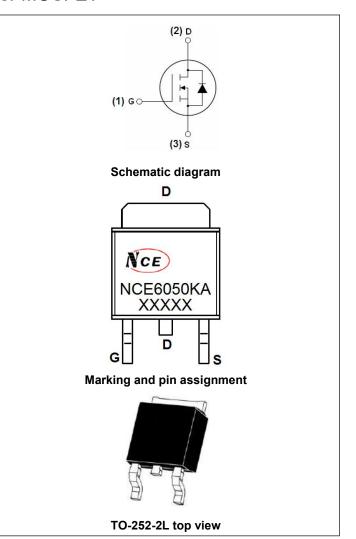
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6050KA	NCE6050KA	TO-252-2L	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	50	А
Drain Current-Continuous(T _C =100°ℂ)	I _D (100℃)	35.4	Α
Pulsed Drain Current	I _{DM}	200	Α
Maximum Power Dissipation	P _D	85	W
Derating factor		0.57	W/℃
Single pulse avalanche energy (Note 5)	Eas	200	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$

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NCE6050KA

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	Rejc	1.8	°C/W	
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Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.15	1.6	2.5	V
Dunin Course On State Besistance		V _{GS} =10V, I _D =20A	-	12	13.8	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	16	19.2	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A	18	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ 00\/\/ 0\/	-	1630	-	PF
Output Capacitance	Coss	V _{DS} =30V,V _{GS} =0V, - 113		-	PF	
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	97	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t _{d(on)}		-	7.4	-	nS
Turn-on Rise Time	t _r	V_{DD} =30V, R_L =6.7 Ω	-	5.1	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =3Ω	-	28.2	-	nS
Turn-Off Fall Time	t _f		-	5.5	-	nS
Total Gate Charge	Qg	V 00VI 00A	-	39		nC
Gate-Source Charge	Q _{gs}	V_{DS} =30V, I_D =20A, - 7			nC	
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	8.5		nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	50	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =20A	-	28	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	40	-	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is negl	igible (turi	n-on is do	ominated b	y LS+LD

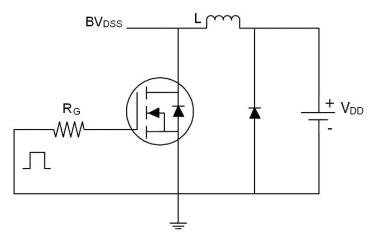
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$.
- **4.** Guaranteed by design, not subject to production
- **5.** EAS condition : Tj=25 $^{\circ}$ C,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25 Ω

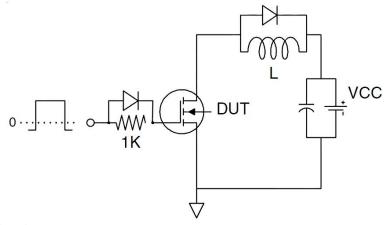


Test Circuit

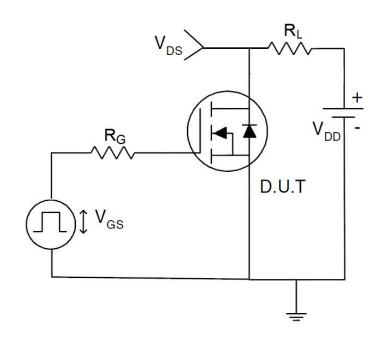
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit







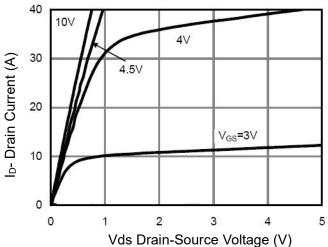


Figure 1 Output Characteristics

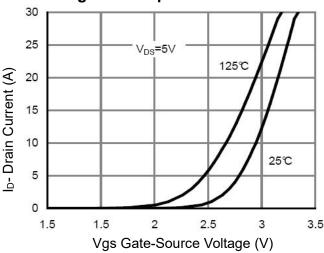


Figure 2 Transfer Characteristics

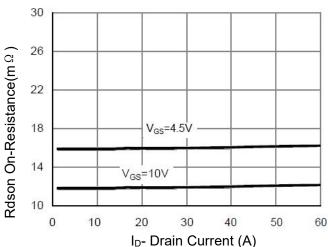


Figure 3 Rdson-Drain Current

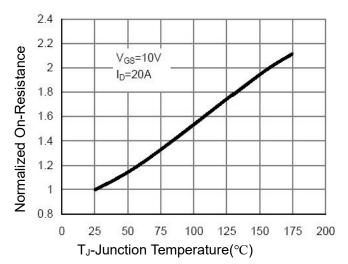
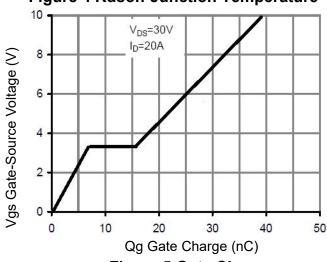


Figure 4 Rdson-Junction Temperature



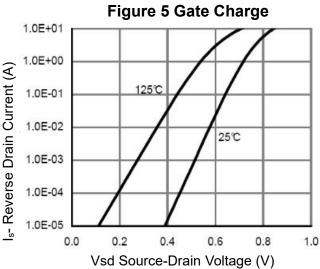


Figure 6 Source- Drain Diode Forward



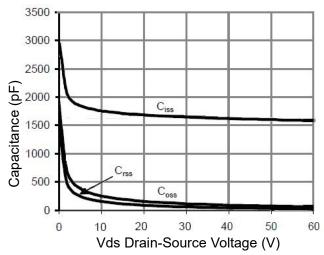
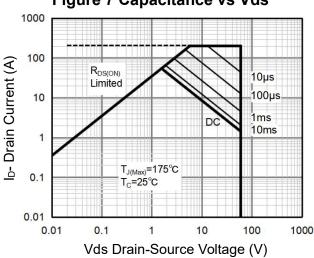
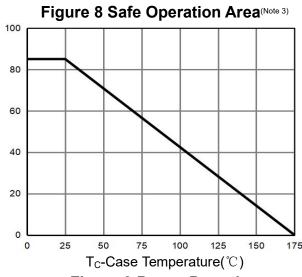


Figure 7 Capacitance vs Vds





Power Dissipation (W)

Figure 9 Power De-rating

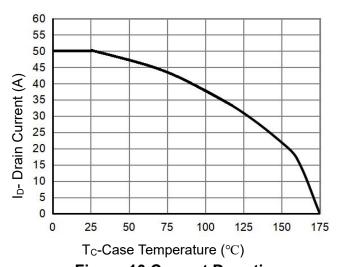


Figure 10 Current De-rating

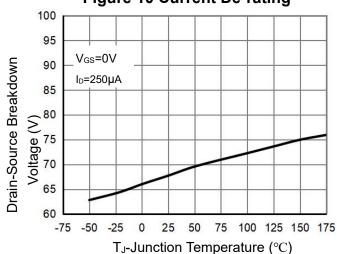


Figure 11 BV_{DSS}-Junction Temperature

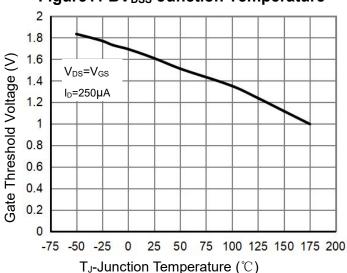


Figure 12 V_{GS(th)}-Junction Temperature



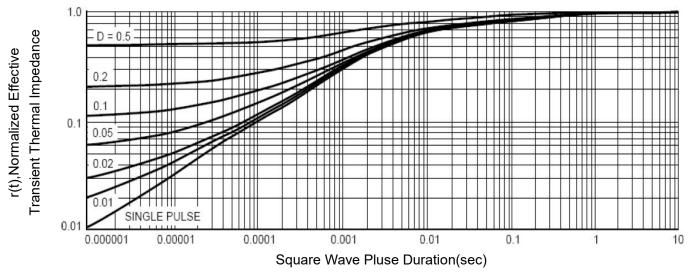
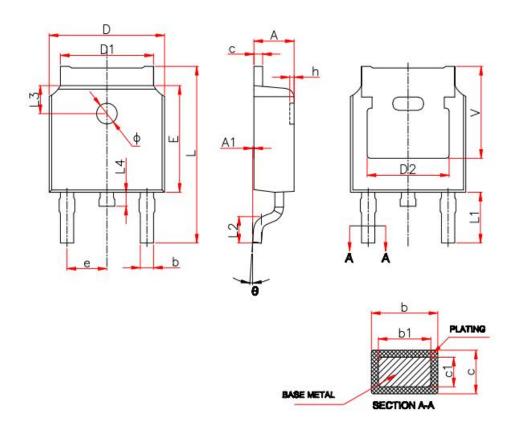


Figure 13 Normalized Maximum Transient Thermal Impedance



TO-252 Package Information



Cumbal	Millimeters		
Symbol -	Min.	Max.	
Α	2.20	2.40	
A1	0.00 0.1		
b	0.66 0.8		
b1	0.73 0.7		
С	0.46 0.5		
c1	0.50	0.52	
D	6.50	6.70	
D1	5.10	5.46	
D2	4.83 REF.		
E	6.00	6.20	
е	2.19	2.39	
L	9.80	10.40	
L1	2.90 REF.		
L2	1.40 1.70		
L3	1.60 REF.		
L4	0.60	1.00	
Ф	1.10	1.30	
θ	0°	8°	



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